



4D Printing and Society-Preparing for the 4D Printing of the Next Future

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Message from the Guest Editors

Dear Colleagues,

Since the emergence of the 4D printing paradigm in 2013, approximately two thousand high-level research works have been published, and while there is an intense desire to pave the field from a scientific perspective, the maturity of the technology reminds us of additive manufacturing from several decades earlier, and the inherent difficulties in its easy use in society through manufacturing industries. To overcome this fast-approaching issue, it is necessary to (i) further investigate 4D printing by simultaneously considering the potentiality of the use and improved performances of 4D-printed devices in a way to highlight the avenues of satisfactory developments, and (ii) carry out more prospective approaches and disruptive ideas.

This Special Issue aims to explore a fraction of the long road of short-, mid-, and long-term (possible) robust and exciting applications empowering the 4D printing potential (with its many degrees of freedom relative to 3D printing).

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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